



SYMBOLS	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.203 REF.		
b	0.12	0.17	0.22
b1	0.07	0.12	0.17
D	2.45	2.50	2.55
E	2.45	2.50	2.55
e	0.35 BSC		
L	0.20	0.25	0.30
K	0.20	—	—
D2	1.35	1.40	1.45
E2	1.35	1.40	1.45

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA



PERICOM[®] A PRODUCT LINE OF DIODES INCORPORATED
ENABLING SERIAL CONNECTIVITY

DATE: 06/18/19

DESCRIPTION: 24-Contact, Very Very Thin Quad Flat No-Lead (TQFN)

PACKAGE CODE: ZR (ZR24)

DOCUMENT CONTROL #: PD-2237

REVISION: A